Change in menu Project

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer	Alternate PartNumber	Alternate Manufacturer
!PCB	1		Printed Circuit Board		XX####	Any	•	-
C1, C2, C3	3	120uF	CAP, AL, 120uF, 20V, +/-20%, 0.025 ohm, SMD	F61	20SVPF120M	Sanyo		
C4, C5	2	1uF	CAP, CERM, 1uF, 100V, +/-20%, C Series, 1206	1206	C3216X7R2A105M	TDK	-	-
C6	1	330uF	16VDC 330UF 16MOHM 10X12.7MM	SMD	16SVP330M	Panasonic Electronic Compor	-	-
C7, Cx1	2	22uF	CAP, CERM, 22uF, 16V, +/-10%, X5R, 1206	1206	GRM31CR61C226KE15 L	MuRata		
C8, C11	2	100pF	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	0603	GRM1885C1H101JA01 D	MuRata	-	-
C12	1	0.047uF	CAP, CERM, 0.047uF, 25V, +/-10%, X7R, 0603	0603	GRM188R71E473KA01 D	MuRata	-	-
C13	1	0.47uF	CAP, CERM, 0.47uF, 25V, +/-10%, X5R, 0603	0603	GRM188R61E474KA12 D	MuRata		
C14, C15	2	15pF	CAP, CERM, 15pF, 50V, +/-5%, C0G/NP0, 0603	0603	GRM1885C1H150JA01	MuRata		
Cc	1	0.047uF	CAP, CERM, 0.047uF, 50V, +/-10%, X7R, 0603	0603	GRM188R71H473KA61 D	MuRata		
Chf	1	330pF	CAP, CERM, 330pF, 50V, +/-5%, C0G/NP0, 0603	0603	C1608C0G1H331J	TDK		-
COMP, EN, SS	3	White	Test Point, TH, Miniature, White	Keystone5002	5002	Keystone	-	-
Csb	1	820pF	CAP, CERM, 820pF, 50V, +/-5%, C0G/NP0, 0603	0603	GRM1885C1H821JA01	MuRata		
Css	1	0.1uF	CAP, CERM, 0.1uF, 25V, +/-10%, X7R, 0603	0603	GRM188R71E104KA01	MuRata	-	-
Cvcc	1	4.7µF	CAP CER 4.7UF 10V 10% X6S 0603	0603 (1608 Metric)	C1608X6S1A475K	TDK Corporation	-	-
FID1, FID2,	3	pi	Fiducial mark. There is nothing to buy or mount.	Fiducial	N/A	N/A	-	-
FID3 H1, H2, H3,	4		Machine Screw, Round, #4-40 x 1/4, Nylon, Philips	Screw	NY PMS 440 0025 PH	B&F Fastener Supply	-	-
H4 H5, H6, H7,	4		panhead Standoff, Hex, 0.5"L #4-40 Nylon	Standoff	1902C	Keystone	-	-
H8 HG, LG,	4	White	Test Point, Miniature, White, TH	Keystone5002	5002	Keystone		
PRI, SEC		winte				-		
J2, J4, VIN, VOUT	4		Standard Banana Jack, Uninsulated, 5.5mm	Keystone_575-4	575-4	Keystone		
LBL1	1		Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650"H x 0.200"W	THT-14-423-10	Brady	-	-
PGND, PGND1, V-, VO-	4	Black	Test Point, TH, Multipurpose, Black	Keystone5011	5011	Keystone	-	-
Q1, Q2	2	80V	MOSFET, N-CH, 80V, 55A, PG-TDSON-8	PG-TDSON-8	BSC123N08NS3 G	Infineon Technologies	-	-
R2, R3	2	182	RES, 182 ohm, 1%, 0.1W, 0603	0603	CRCW0603182RFKEA			
R5, R6, R7, R8, R11	5	0	RES, 0 ohm, 5%, 0.1W, 0603	0603	ERJ-3GEY0R00V	Panasonic	-	-
R9	1	49.9k	RES, 49.9k ohm, 1%, 0.1W, 0603	0603	CRCW060349K9FKEA	Vishay-Dale	-	-
R10	1	3.3	RES, 3.3 ohm, 5%, 0.1W, 0603	0603	CRCW06033R30JNEA	Vishay-Dale	-	-
R12	1	8.66k	RES, 8.66k ohm, 1%, 0.1W, 0603	0603	CRCW06038K66FKEA	Vishay-Dale	-	-
R13	1	100k	RES, 100k ohm, 1%, 0.1W, 0603	0603	CRCW0603100KFKEA	Vishay-Dale		
R19	1	348	RES, 348 ohm, 1%, 0.1W, 0603	0603	CRCW0603348RFKEA			
RB	1	9.53k	RES, 9.53k ohm, 1%, 0.1W, 0603	0603	CRCW06039K53FKEA	Vishay-Dale		
Rc	1	49.9k	RES, 59.0k ohm, 1%, 0.1W, 0603	0603	CRCW060359K0FKEA	Vishay-Dale	-	-
RS+, V+, VO+	3	Red	Test Point, Miniature, Red, TH	Keystone5000	5000	Keystone		
RS-	1	Black	Test Point, Miniature, Black, TH	Keystone5001	5001	Keystone		
Rs1	1	0.010	RES 0.01 OHM 1W 1% 2512 SMD	2512			-	-
Rs2	1	0.010	RES, 0.010 ohm, 1%, 1W, 2512	2512			-	-
Rsb1, Rsb2	2	34.0	RES 34 OHM 1/2W 1% 1210 SMD	1210	ERJ-14NF34R0U	Panasonic Electronic Compor		
Rsyn	1	40.2k	RES, 40.2k ohm, 1%, 0.1W, 0603	0603	CRCW060340K2FKEA		-	-
Rt	1	84.5k	RES, 84.5k ohm, 1%, 0.1W, 0603	0603	CRCW060384K5FKEA	Vishay-Dale		
SGND U1	1	Black	Test Point, TH, Miniature, Black	Keystone5001 eg: 0603, used in	5001 LM5122MH	Keystone TI	-	-
X1	1			PnP report eg: 0603, used in	HPH6-0158L	Coilcraft Inc	-	-
		100 5		PnP report			-	-
C10	0	100pF	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	0603	GRM1885C1H101JA01 D	MuRata	-	-
D1	0	0.77V	Diode, Schottky, 100V, 1A, PowerDI123	PowerDI123	DFLS1100-7	Diodes Inc.	-	-
R4	0	DNP	RES, 158k ohm, 1%, 0.1W, 0603	0603	CRCW0603158KFKEA	Vishay-Dale	-	-
R14	0	DNP	RES, 0 ohm, 5%, 0.1W, 0603	0603	ERJ-3GEY0R00V	Panasonic	-	-

Notes:

Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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